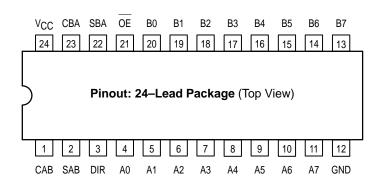
Low-Voltage CMOS Octal Transceiver/Registered Transceiver With 5V-Tolerant Inputs and Outs

With 5V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The MC74LCX646 is a high performance, non-inverting octal transceiver/registered transceiver operating from a 2.7 to 3.6V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A V_I specification of 5.5V allows MC74LCX646 inputs to be safely driven from 5V devices. The MC74LCX646 is suitable for memory address driving and all TTL level bus oriented transceiver applications.

Data on the A or B bus will be clocked into the registers as the appropriate clock pin goes from a LOW-to-HIGH logic level. Output Enable (OE) and DIR pins are provided to control the transceiver outputs. In the transceiver mode, data present at the high impedance port may be stored in either the A or the B register or in both. The select controls (SBA, SAB) can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus will receive data when the enable OE is active LOW. In the isolation mode (OE HIGH), A data may be stored in the B register or B data may be stored in the A register. Only one of the two buses, A or B, may be driven at one time.

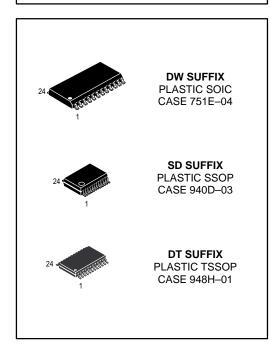
- Designed for 2.7 to 3.6V V_{CC} Operation
- 5V Tolerant Interface Capability With 5V TTL Logic
- Supports Live Insertion and Withdrawal
- IOFF Specification Guarantees High Impedance When VCC = 0V
- LVTTL Compatible
- LVCMOS Compatible
- 24mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current in All Three Logic States (10μA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500mA
- ESD Performance: Human Body Model >2000V; Machine Model >200V



MC74LCX646



LOW-VOLTAGE CMOS OCTAL TRANSCEIVER/ REGISTERED TRANSCEIVER



PIN NAMES

REV 2

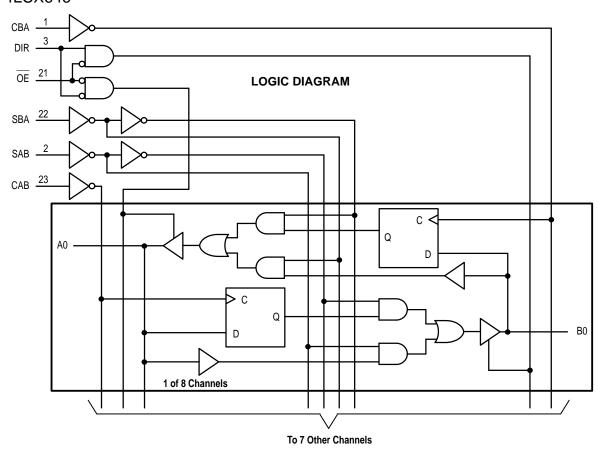
Pins	Function
A0-A7 B0-B7 CAB, CBA SAB, <u>SB</u> A DIR, OE	Side A Inputs/Outputs Side B Inputs/Outputs Clock Pulse Inputs Select Control Inputs Output Enable Inputs



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MC74LCX646



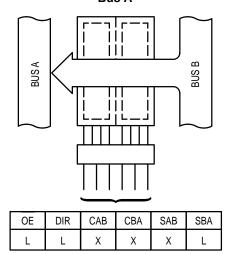
FUNCTION TABLE

		In	puts			Data	Ports	Our condition of Manager
OE	DIR	CAB	СВА	SAB	SBA	An	Bn	Operating Mode
Н	Х					Input	Input	
		1	1	Х	Х	Х	Х	Isolation, Hold Storage
		↑	↑	Х	Х	l h X X	X X I h	Store A and/or B Data
L	Н					Input	Output	
		1	X*	L	Х	L H	L H	Real Time A Data to B Bus
				Н	Х	Х	QA	Stored A Data to B Bus
		1	X*	L	Х	l h	LH	Real Time A Data to B Bus; Store A Data
				Н	Х	L H	QA QA	Clock A Data to B Bus; Store A Data
L	L					Output	Input	
		X*	1	Х	L	L H	LH	Real Time B Data to A Bus
				Х	Н	QB	Х	Stored B Data to A Bus
		X*	1	Х	L	L H	l h	Real Time B Data to A Bus; Store B Data
				Х	Н	QB QB	L H	Clock B Data to A Bus; Store B Data

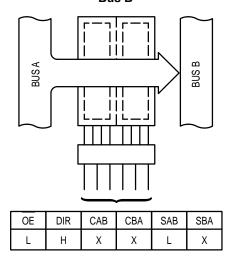
H = High Voltage Level; h = High Voltage Level One Setup Time Prior to the Low-to-High Clock Transition; L = Low Voltage Level; I = Low Voltage Level One Setup Time Prior to the Low-to-High Clock Transition; X = Don't Care; 1 = Low-to-High Clock Transition; 2 = NOT Low-to-High Clock Transition; QA = A input storage register; QB = B input storage register; * = The clocks are not internally gated with either the Output Enables or the Source Inputs. Therefore, data at the A or B ports may be clocked into the storage registers, at any time. For I_{CC} reasons, Do Not Float Inputs.

BUS APPLICATIONS

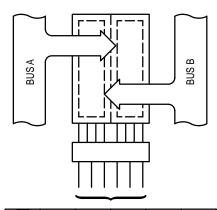
Real Time Transfer – Bus B to Bus A



Real Time Transfer – Bus A to Bus B

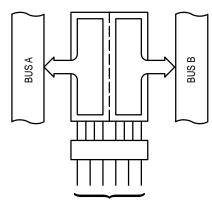


Store Data from Bus A, Bus B or Busses A and B



OE	DIR	CAB	CBA	SAB	SBA
н×х	X X X	\rightarrow X \rightarrow	X ← ←	X X X	X X X

Transfer Storage Data to Bus A or Bus B



OE	DIR	CAB	CBA	SAB	SBA
L	LH	X H or L	H or L X	X	H X

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
Vcc	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \le V_{\parallel} \le +7.0$		V
Vo	DC Output Voltage	$-0.5 \le V_{O} \le +7.0$	Output in 3-State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1.	V
IK	DC Input Diode Current	– 50	V _I < GND	mA
loк	DC Output Diode Current	-50	V _O < GND	mA
		+50	VO > VCC	mA
Io	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
^I GND	DC Ground Current Per Ground Pin	±100		mA
TSTG	Storage Temperature Range	-65 to +150		°C

Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

1. Output in HIGH or LOW State. Io absolute maximum rating must be observed.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
Vcc	Supply Voltage Operating Data Retention Only	2.0 1.5	3.3 3.3	3.6 3.6	٧
VI	Input Voltage	0		5.5	V
Vo	Output Voltage (HIGH or LOW State) (3–State)	0 0		V _{CC} 5.5	V
loн	HIGH Level Output Current, V _{CC} = 3.0V - 3.6V			-24	mA
lOL	LOW Level Output Current, V _{CC} = 3.0V – 3.6V			24	mA
loн	HIGH Level Output Current, V _{CC} = 2.7V - 3.0V			-12	mA
lOL	LOW Level Output Current, V _{CC} = 2.7V – 3.0V			12	mA
TA	Operating Free-Air Temperature	-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V_{IN} from 0.8V to 2.0V, $V_{CC} = 3.0V$	0		10	ns/V

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°C	to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
VIH	HIGH Level Input Voltage (Note 2.)	$2.7V \le V_{CC} \le 3.6V$	2.0		V
V _{IL}	LOW Level Input Voltage (Note 2.)	$2.7V \le V_{CC} \le 3.6V$		0.8	V
Vон	HIGH Level Output Voltage	$2.7V \le V_{CC} \le 3.6V; I_{OH} = -100\mu A$	V _{CC} – 0.2		V
		$V_{CC} = 2.7V; I_{OH} = -12mA$	2.2		
		$V_{CC} = 3.0V; I_{OH} = -18mA$	2.4		
		$V_{CC} = 3.0V; I_{OH} = -24mA$	2.2		
VOL	LOW Level Output Voltage	$2.7V \le V_{CC} \le 3.6V$; $I_{OL} = 100\mu A$		0.2	V
		$V_{CC} = 2.7V; I_{OL} = 12mA$		0.4	
		V _{CC} = 3.0V; I _{OL} = 16mA		0.4	
		$V_{CC} = 3.0V; I_{OL} = 24mA$		0.55	

^{2.} These values of V_I are used to test DC electrical characteristics only.

DC ELECTRICAL CHARACTERISTICS (continued)

			T _A = -40°C to +85°C		
Symbol	Characteristic	Condition	Min	Max	Unit
Ц	Input Leakage Current	$2.7V \le V_{CC} \le 3.6V; \ 0V \le V_{I} \le 5.5V$		±5.0	μΑ
loz	3–State Output Current	$2.7 \le V_{CC} \le 3.6V$; $0V \le V_O \le 5.5V$; $V_I = V_{IH}$ or V_{IL}		±5.0	μΑ
lOFF	Power-Off Leakage Current	$V_{CC} = 0V$; V_I or $V_O = 5.5V$		10	μΑ
ICC	Quiescent Supply Current	$2.7 \le V_{CC} \le 3.6V$; $V_I = GND$ or V_{CC}		10	μΑ
		$2.7 \le V_{CC} \le 3.6V$; $3.6 \le V_I$ or $V_O \le 5.5V$		±10	μΑ
ΔlCC	Increase in I _{CC} per Input	$2.7 \le V_{CC} \le 3.6V; V_{IH} = V_{CC} - 0.6V$		500	μΑ

AC CHARACTERISTICS ($t_R = t_F = 2.5 \text{ns}$; $C_L = 50 \text{pF}$; $R_L = 500 \Omega$)

				Lin	nits		
				T _A = -40°	C to +85°C		
			V _{CC} = 3.	0V to 3.6V	Vcc	= 2.7V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
f _{max}	Clock Pulse Frequency	3	150				MHz
^t PLH ^t PHL	Propagation Delay Input to Output	1	1.5 1.5	7.0 7.0	1.5 1.5	8.0 8.0	ns
^t PLH ^t PHL	Propagation Delay Clock to Output	3	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t _{PLH} t _{PHL}	Propagation Delay Select to Output	1	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
^t PZH ^t PZL	Output Enable Time to High and Low Level	2	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
^t PHZ ^t PLZ	Output Disable Time From High and Low Level	2	1.5 1.5	8.5 8.5	1.5 1.5	9.5 9.5	ns
t _S	Setup Time, HIGH or LOW Data to Clock	3	2.5		2.5		ns
t _h	Hold Time, HIGH or LOW Data to Clock	3	1.5		1.5		ns
t _W	Clock Pulse Width, HIGH or LOW	3	3.3		3.3		ns
^t OSHL ^t OSLH	Output-to-Output Skew (Note 3.)			1.0 1.0			ns

^{3.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshl) or LOW-to-HIGH (tosl); parameter guaranteed by design.

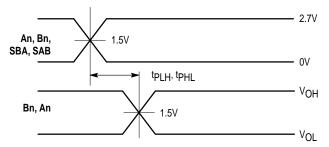
DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
VOLP	Dynamic LOW Peak Voltage (Note 4.)	$V_{CC} = 3.3V$, $C_L = 50pF$, $V_{IH} = 3.3V$, $V_{IL} = 0V$		0.8		V
V _{OLV}	Dynamic LOW Valley Voltage (Note 4.)	$V_{CC} = 3.3V$, $C_L = 50pF$, $V_{IH} = 3.3V$, $V_{IL} = 0V$		0.8		V

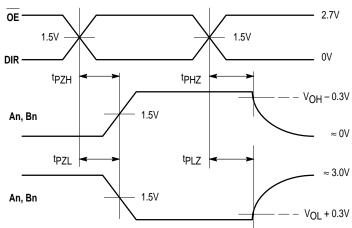
^{4.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	7	pF
C _{I/O}	Input/Output Capacitance	$V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance	10MHz, $V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC}	25	pF

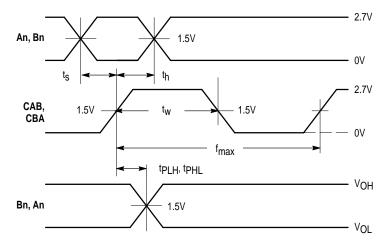


WAVEFORM 1 – SAB to B and SBA to A, An to Bn PROPAGATION DELAYS $t_R=t_F=2.5 ns,\,10\%$ to $90\%;\,f=1MHz;\,t_W=500 ns$



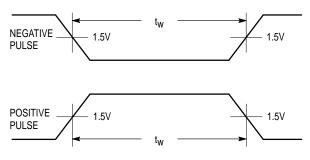
WAVEFORM 2 – OE/DIR to An/Bn OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.5 ns$, 10% to 90%; f = 1 MHz; $t_W = 500 ns$

Figure 1. AC Waveforms



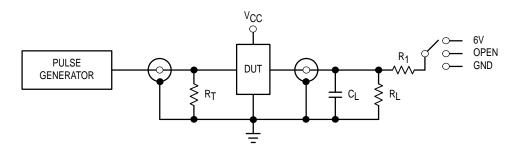
WAVEFORM 3 – CLOCK to Bn/An PROPAGATION DELAYS, CLOCK MINIMUM PULSE WIDTH, An/Bn to CLOCK SETUP AND HOLD TIMES

 $t_R = t_F = 2.5$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns except when noted



WAVEFORM 4 – INPUT PULSE DEFINITION $t_R = t_F = 2.5$ ns, 10% to 90% of 0V to 2.7V

Figure 2. AC Waveforms

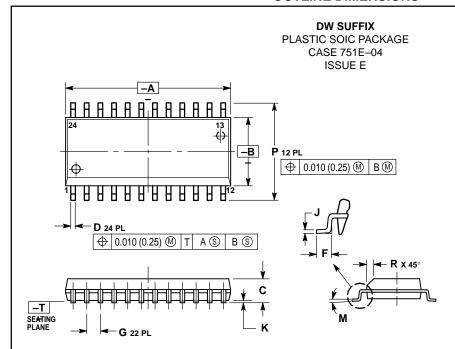


TEST	SWITCH
tPLH, tPHL	Open
tPZL, tPLZ	6V
Open Collector/Drain tpLH and tpHL	6V
^t PZH ^{, †} PHZ	GND

 C_L = 50pF or equivalent (Includes jig and probe capacitance) R_L = R_1 = 500 Ω or equivalent R_T = Z_{OUT} of pulse generator (typically 50 Ω)

Figure 3. Test Circuit

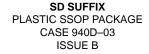
OUTLINE DIMENSIONS



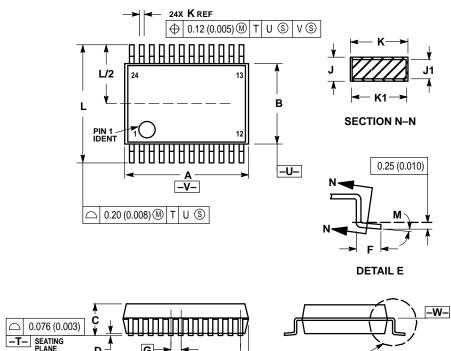
NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14 5M 1982
- CONTROLLING DIMENSION: MILLIMETER.
- DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN EXCESS OF D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	15.25	15.54	0.601	0.612
В	7.40	7.60	0.292	0.299
С	2.35	2.65	0.093	0.104
D	0.35	0.49	0.014	0.019
F	0.41	0.90	0.016	0.035
G	1.27 BSC		0.050 BSC	
J	0.23	0.32	0.009	0.013
K	0.13	0.29	0.005	0.011
M	0°	8°	0°	8°
Р	10.05	10.55	0.395	0.415
R	0.25	0.75	0.010	0.029



DETAIL E



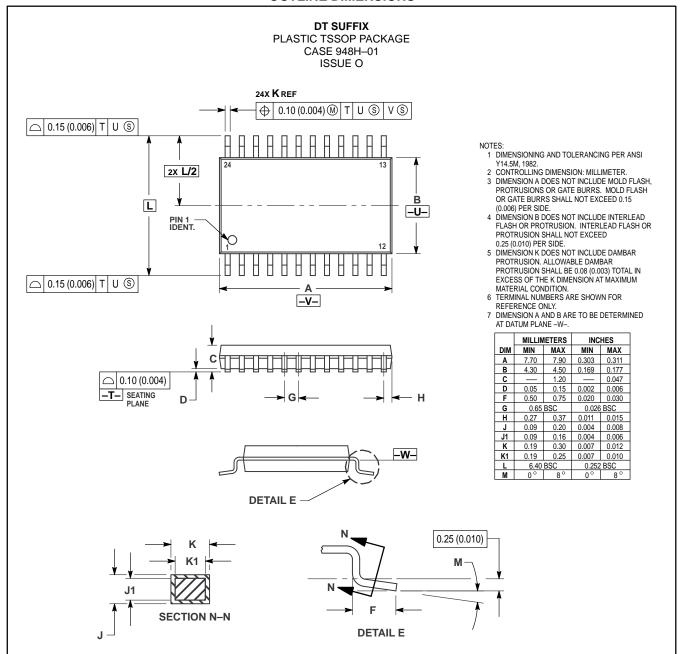
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- NOTES:
 4 DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
 5 CONTROLLING DIMENSION: MILLIMETER.
- 6 DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- OR GATE BURRS SHALL NOT EXCELS 0.13
 (0.006) PER SIDE.
 7 DIMENSION B DOES NOT INCLUDE INTERLEAD
 FLASH OR PROTRUSION. INTERLEAD FLASH OR
 PROTRUSION SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 8 DIMENSION K DOES NOT INCLUDE DAMBAR
- DIMENSION K DOES NOT INCLUDE DAMBAR
 PROTRUSION/INTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.13 (0.005) TOTAL IN
 EXCESS OF K DIMENSION AT MAXIMUM
 MATERIAL CONDITION. DAMBAR INTRUSION SHALL NOT REDUCE DIMENSION K BY MORE THAN 0.07 (0.002) AT LEAST MATERIAL CONDITION.
- 9 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 10 DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE –W–.

	MILLIN	METERS	INCHES	
DIM	MIN	MAX	MIN	MAX
Α	8.07	8.33	0.317	0.328
В	5.20	5.38	0.205	0.212
С	1.73	1.99	0.068	0.078
D	0.05	0.21	0.002	0.008
F	0.63	0.95	0.024	0.037
G	0.65 BSC		0.026 BSC	
Н	0.44	0.60	0.017	0.024
J	0.09	0.20	0.003	0.008
J1	0.09	0.16	0.003	0.006
K	0.25	0.38	0.010	0.015
K1	0.25	0.33	0.010	0.013
L	7.65	7.90	0.301	0.311
M	0 °	8 °	0 °	8 °

OUTLINE DIMENSIONS



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